



#### N-CHANNEL ENHANCEMENT MODE MOSFET

#### **Product Summary**

V <sub>(BR)DSS</sub>	R <sub>DS(ON)</sub> max	I <sub>D</sub> max T <sub>A</sub> = +25°C
	$28m\Omega$ @ $V_{GS} = 10V$	5.8A
30V	$42m\Omega$ @ $V_{GS} = 4.5V$	4.8A
	82mΩ @ V <sub>GS</sub> = 3V	2.0A

#### **Description**

This MOSFET has been designed to minimize the on-state resistance (R<sub>DS(ON)</sub>) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

## **Applications**

- Battery Charging
- Power Management Functions
- DC-DC Converters
- Portable Power Adaptors

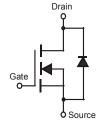
## **Features and Benefits**

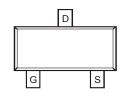
- Low On-Resistance
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

#### **Mechanical Data**

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound.
   UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin annealed over Copper leadframe.
   Solderable per MIL-STD-202, Method 208 @3
- Terminals Connections: See Diagram Below
- Weight: 0.008 grams (approximate)







Top View

Internal Schematic

Top View

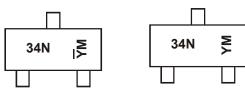
### Ordering Information (Note 4 & 5)

Part Number	Compliance	Case	Packaging
DMN3404L-7	Standard	SOT23	3000/Tape & Reel
DMN3404LQ-7	Automotive	SOT23	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
- 2. See http://www.diodes.com/quality/lead\_free.htmlfor more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Automotive and standard products are electrically and thermally the same, except where specified. For more information, please refer to http://www.diodes.com/quality/product\_compliance\_definitions/.
- 5. For packaging details, go to Diodes website at http://www.diodes.com/products/packages.html.

## **Marking Information**



Chengdu A/T Site

34N = Product Type Marking Code

YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)  $\overline{Y}_M$  = Date Code Marking for CAT (Chengdu Assembly/ Test site) Y or  $\overline{Y}$  = Year (ex: A = 2013)

M = Month (ex: 9 = September)

w = worth (ex. 9 = Sept

Date Code Key

Date Code Rey												
Year	200	9	2010		2011	20	12	2013		2014	2	2015
Code	W		X		Y		7	Α		В		С
•		•										
Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	N	D

Shanghai A/T Site



## Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units		
Drain-Source Voltage (Note	V <sub>DSS</sub>	30	V		
Gate-Source Voltage			V <sub>GSS</sub>	±20	V
Continuous Drain Current (Note 6) V <sub>GS</sub> = 10V	Steady State	$T_A = -40^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	I <sub>D</sub>	4.6 4.2 3.0	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = 10V	Steady State	$T_A = -40^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	I <sub>D</sub>	6.2 5.8 4.0	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = 4.5V	Steady State	$T_A = -40^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	I <sub>D</sub>	5.2 4.8 3.2	А
Continuous Drain Current (Note 7) V <sub>GS</sub> = 3V	Steady State	$T_A = -40^{\circ}C$ $T_A = +25^{\circ}C$ $T_A = +85^{\circ}C$	I <sub>D</sub>	2.2 2.0 1.0	А
Pulsed Drain Current			I <sub>DM</sub>	30	A

### **Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	P <sub>D</sub>	0.72	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C	R <sub>θJA</sub>	173	°C/W
Power Dissipation (Note 7)	P <sub>D</sub>	1.4	W
Thermal Resistance, Junction to Ambient @T <sub>A</sub> = +25°C	R <sub>0JA</sub>	90	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

Notes:

<sup>6.</sup> Device mounted on FR-4 substrate PC board, 2oz copper, with minimum recommended pad layout.7. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal bias to bottom layer 1inch square copper plate.

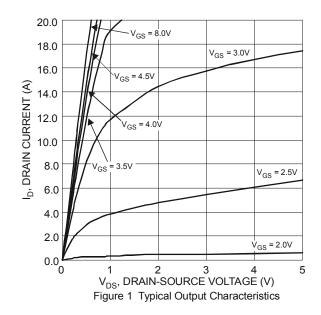


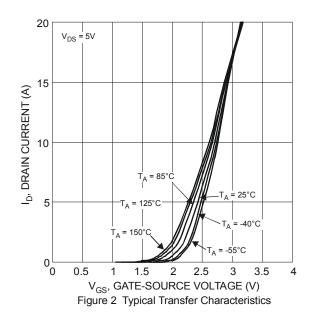
# $\textbf{Electrical Characteristics} \ (\textcircled{@} T_{A} = +25 ^{\circ} C, \ unless \ \ otherwise \ specified.)$

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 8)						
Drain-Source Breakdown Voltage	BV <sub>DSS</sub>	30	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$
Zero Gate Voltage Drain Current T <sub>J</sub> = +25°C	I <sub>DSS</sub>	_	_	1.0	μA	V <sub>DS</sub> = 30V, V <sub>GS</sub> = 0V
Gate-Source Leakage	I <sub>GSS</sub>	_	_	±100	nA	V <sub>GS</sub> = ±20V, V <sub>DS</sub> = 0V
ON CHARACTERISTICS (Note 8)						
Gate Threshold Voltage	V <sub>GS(th)</sub>	1.0	1.5	2.0	V	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$
Static Drain Source On Registence T. = 40°C (Note 9)	D	_	23	27	_	$V_{GS} = 4.5V, I_D = 4.8A$
Static Drain-Source On-Resistance T <sub>J</sub> = -40°C (Note 9)	R <sub>DS(ON)</sub>	_	57	74	_	V <sub>GS</sub> =3V, I <sub>D</sub> =2A
		_	24	28		V <sub>GS</sub> = 10V, I <sub>D</sub> = 5.8A
Static Drain-Source On-Resistance T <sub>J</sub> = +25°C	R <sub>DS(ON)</sub>	_	33	42	mΩ	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 4.8A
		_	63	82		V <sub>GS</sub> =3V, I <sub>D</sub> =2A
Static Drain-Source On-Resistance T <sub>J</sub> = +85°C (Note 9)	R <sub>DS(ON)</sub>	_	71	95	mΩ	V <sub>GS</sub> =3V, I <sub>D</sub> =2A
Forward Transfer Admittance	Y <sub>fs</sub>	_	10	_	S	V <sub>DS</sub> = 5V, I <sub>D</sub> = 5.8A
Diode Forward Voltage	V <sub>SD</sub>	_	0.75	1.0	V	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1A
DYNAMIC CHARACTERISTICS (Note 10)						
Input Capacitance	C <sub>iss</sub>	_	498	_	pF	
Output Capacitance	Coss	_	52	_	pF	$V_{DS} = 15V, V_{GS} = 0V, f = 1.0MHz$
Reverse Transfer Capacitance	C <sub>rss</sub>	_	45	_	pF	
Gate Resistance	Rg	_	1.75	2.8	Ω	V <sub>DS</sub> = 0V, V <sub>GS</sub> = 0V, f = 1MHz
Total Gate Charge (V <sub>GS</sub> = 3V)	Qg	_	3.8	5.3	nC	V <sub>GS</sub> = 3V, V <sub>DS</sub> = 15V, I <sub>D</sub> = 1A
Total Gate Charge (V <sub>GS</sub> = 4.5V)	Qg	_	5.3	7.5	nC	
Total Gate Charge (V <sub>GS</sub> = 10V)	Qg	_	11.3	16	nC	V <sub>GS</sub> = 10V/4.5V, V <sub>DS</sub> = 15V,
Gate-Source Charge	Qgs	_	1.4	_	nC	I <sub>D</sub> = 5.8A
Gate-Drain Charge	Q <sub>gd</sub>	_	2.1	_	nC	
Turn-On Delay Time	t <sub>D(on)</sub>	_	3.41	10	ns	
Turn-On Rise Time	t <sub>r</sub>	_	6.18	13	ns	V <sub>DD</sub> = 15V, V <sub>GS</sub> = 10V,
Turn-Off Delay Time	t <sub>D(off)</sub>	_	13.92	28	ns	$R_L = 2.6\Omega$ , $R_G = 3\Omega$
Turn-Off Fall Time	t <sub>f</sub>	_	2.84	10	ns	

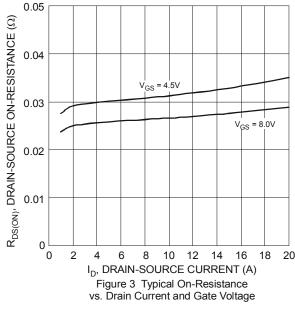
Notes:

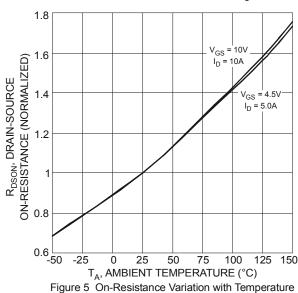
- 8. Short duration pulse test used to minimize self-heating effect.
  9. Guaranteed by design and 25°C data. Not subject to production testing 10. Guaranteed by design. Not subject to production testing.

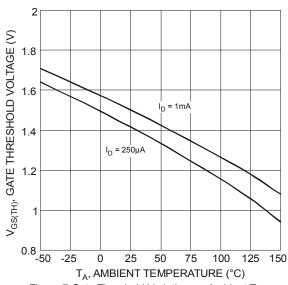














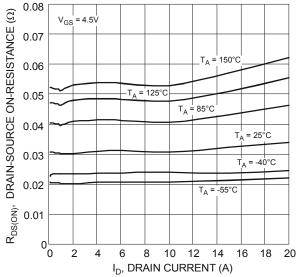


Figure 4 Typical On-Resistance vs. Drain Current and Temperature

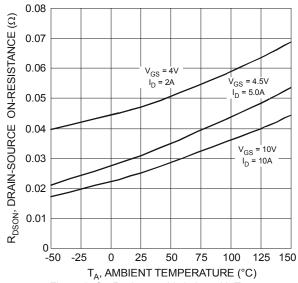


Figure 6 On-Resistance Variation with Temperature

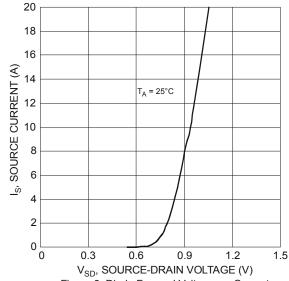


Figure 8 Diode Forward Voltage vs. Current



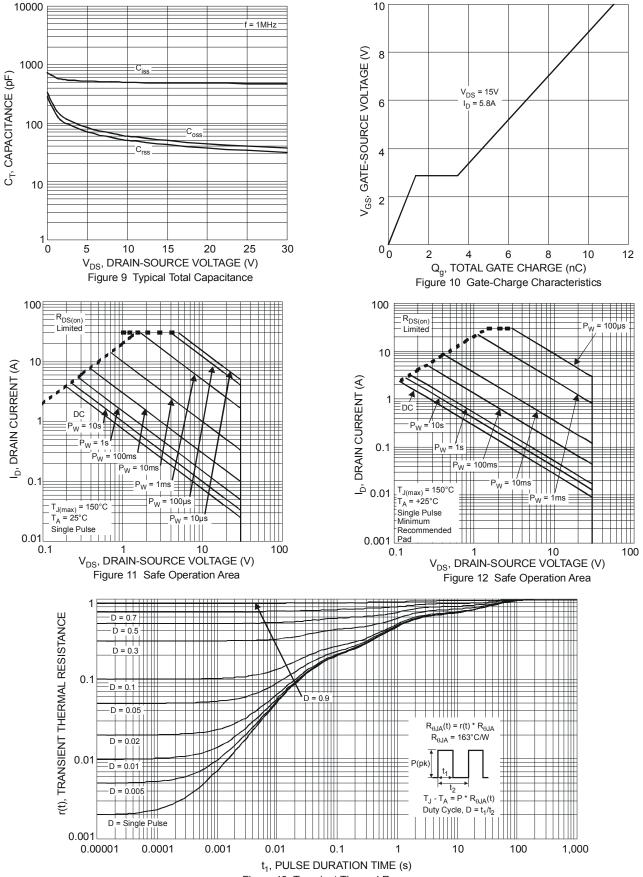
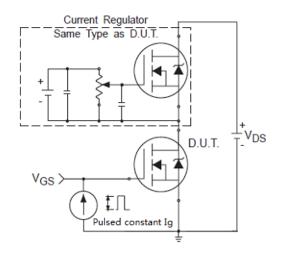
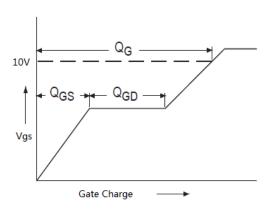


Figure 13 Transient Thermal Response

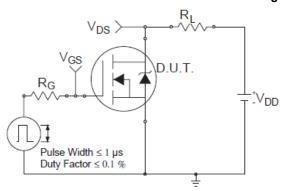


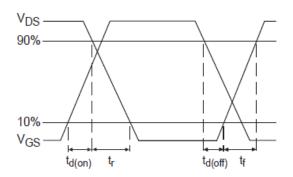
#### **Gate Charge Test Circuit and Waveform**





### **Switching Test Circuit and Waveform**

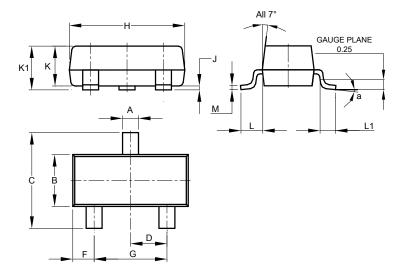






# **Package Outline Dimensions**

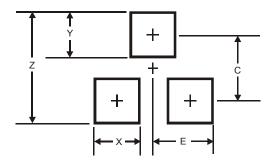
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for latest version.



SOT23								
Dim	Min	Max	Тур					
Α	0.37	0.51	0.40					
В	1.20	1.40	1.30					
С	2.30	2.50	2.40					
D	0.89	1.03	0.915					
F	0.45	0.60	0.535					
G	1.78	2.05	1.83					
Н	2.80	3.00	2.90					
J	0.013	0.10	0.05					
K	0.890	1.00	0.975					
K1	0.903	1.10	1.025					
L	0.45	0.61	0.55					
L1	0.25	0.55	0.40					
M	0.085	0.150	0.110					
α	8°							
All Dimensions in mm								

## **Suggested Pad Layout**

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
С	2.0
E	1.35



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